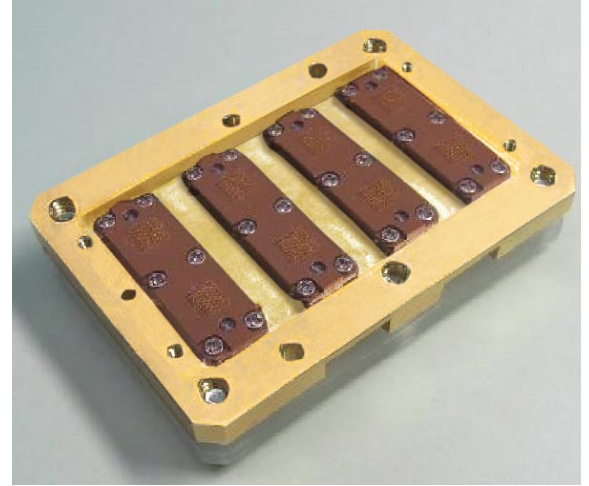
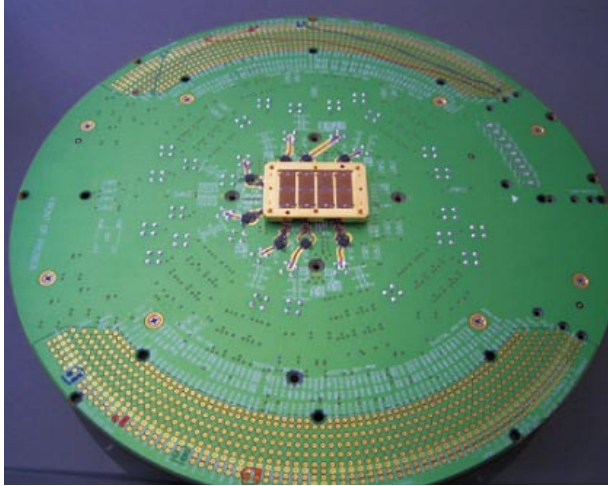


Yokowo Vertical High-Giga Probe Card (Hi-Speed) (YVH series)

yokowo



Yokowo Vertical High-Giga Probe Card

Applications

- Vertical probe design is available for area array electrode layout, which pitch size is more than 160µm

Features

- A stable contact by the probe contactor method.
- Superior signal integrity up to 12GHz.
- Providing Appropriate pattern design by simulation in the electromagnetic field.
- Hand test for characterization capable by same contactor, therefore correlation data can be utilized for wafer test.
- Lower cost Compared to the current probecard contact method.
- Contact Probe can be replaced one by one.
- Available for area array Min Pitch 160µm.
- Multi-site parallel test capability.

Specifications

Pitch	0.5mm	0.4mm	0.3mm	0.2mm	0.16mm
Insertion Loss@-1dB	8GHz	8GHz	5GHz	4GHz	4GHz
Return Loss@-10dB	12GHz	12GHz	6GHz	6GHz	6GHz
Crosstalk@-25db	6GHz	6GHz	TBD**	TBD**	TBD**
Contact Resistance	100mΩ	150mΩ	300mΩ	600mΩ	700mΩ
Current Carrying Capability	1.0A	0.6A	0.4A	0.3A	0.2A
Pin Force	25g	20g	6g	5g	5g
Over Drive	350µm	350µm	250µm	200µm	200µm
Max Pin Count / DUT	250pin	250pin	250pin	250pin	250pin

* To Be Determined